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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-VQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89c51ac2-rltum

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Block Diagram



Notes: 1. 8 analog Inputs/8 Digital I/O 2. 2-Bit I/O Port









Figure 6. Mode Switching Waveforms



Note: In order to prevent any incorrect operation while operating in the X2 mode, users must be aware that all peripherals using the clock frequency as a time reference (UART, timers...) will have their time reference divided by two. For example a free running timer generating an interrupt every 20 ms will then generate an interrupt every 10 ms. A UART with a 4800 baud rate will have a 9600 baud rate.

External Space

Memory Interface

The external memory interface comprises the external bus (port 0 and port 2) as well as the bus control signals (\overline{RD} , \overline{WR} , and ALE).

Figure 13 shows the structure of the external address bus. P0 carries address A7:0 while P2 carries address A15:8. Data D7:0 is multiplexed with A7:0 on P0. Table 17 describes the external memory interface signals.





Table 17.	External Data Memory	Interface Signals
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Signal Name	Туре	Description	Alternative Function
A15:8	0	Address Lines Upper address lines for the external bus.	P2.7:0
AD7:0	I/O	Address/Data Lines Multiplexed lower address lines and data for the external memory.	P0.7:0
ALE	0	Address Latch Enable ALE signals indicates that valid address information are available on lines AD7:0.	-
RD	0	Read Read signal output to external data memory.	P3.7
WR	0	Write Write signal output to external memory.	P3.6

External Bus Cycles

This section describes the bus cycles the A/T89C51AC2 executes to read (see Figure 14), and write data (see Figure 15) in the external data memory.

External memory cycle takes 6 CPU clock periods. This is equivalent to 12 oscillator clock period in standard mode or 6 oscillator clock periods in X2 mode. For further information on X2 mode.

Slow peripherals can be accessed by stretching the read and write cycles. This is done using the M0 bit in AUXR register. Setting this bit changes the width of the RD and WR signals from 3 to 15 CPU clock periods.

For simplicity, the accompanying figures depict the bus cycle waveforms in idealized form and do not provide precise timing information. For bus cycle timing parameters refer to the Section "AC Characteristics".



Dual Data Pointer

Description

The A/T89C51AC2 implements a second data pointer for speeding up code execution and reducing code size in case of intensive usage of external memory accesses. DPTR 0 and DPTR 1 are seen by the CPU as DPTR and are accessed using the SFR addresses 83h and 84h that are the DPH and DPL addresses. The DPS bit in AUXR1 register (see Figure 20) is used to select whether DPTR is the data pointer 0 or the data pointer 1 (see Figure 16).

Figure 16. Dual Data Pointer Implementation



Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare...) are well served by using one data pointer as a "source" pointer and the other one as a "destination" pointer. Hereafter is an example of block move implementation using the two pointers and coded in assembler. The latest C compiler takes also advantage of this feature by providing enhanced algorithm libraries.

The INC instruction is a short (2 Bytes) and fast (6 machine cycle) way to manipulate the DPS bit in the AUXR1 register. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry.

```
; ASCII block move using dual data pointers
; Modifies DPTR0, DPTR1, A and PSW
; Ends when encountering NULL character
; Note: DPS exits opposite to the entry state unless an extra INC AUXR1 is
added
AUXR1EQU0A2h
move:movDPTR, #SOURCE ; address of SOURCE
 incAUXR1 ; switch data pointers
 movDPTR, #DEST ; address of DEST
mv_loop:incAUXR1; switch data pointers
 movxA, @DPTR; get a byte from SOURCE
 incDPTR; increment SOURCE address
 incAUXR1; switch data pointers
 movx@DPTR,A; write the byte to DEST
 incDPTR; increment DEST address
 jnzmv_loop; check for NULL terminator
end_move:
```







Reading the Flash Spaces

User	The following procedure is used to read the User space:						
	 Read one byte in Accumulator by executing MOVC A,@A+DPTR where A+DPTR is the address of the code byte to read. 						
	Note: FCON is supposed to be reset when not needed.						
Extra Row	The following procedure is used to read the Extra Row space and is summarized in Figure 24:						
	 Map the Extra Row space by writing 02h in FCON register. 						
	 Read one byte in Accumulator by executing MOVC A,@A+DPTR with A = 0 and DPTR = FF80h to FFFFh. 						
	Clear FCON to unmap the Extra Row.						
Hardware Security Byte	The following procedure is used to read the Hardware Security space and is summarized in Figure 24:						
	 Map the Hardware Security space by writing 04h in FCON register. 						
	 Read the byte in Accumulator by executing MOVC A,@A+DPTR with A = 0 and DPTR = 0000h. 						
	Clear FCON to unmap the Hardware Security Byte.						



Given Address

Each device has an individual address that is specified in the SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed. To address a device by its individual address, the SADEN mask byte must be 1111 1111b.

For example:

SADDR0101 0110b SADEN1111 1100b Given0101 01XXb

Here is an example of how to use given addresses to address different slaves:

Slave A:SADDR1111 0001b
SADEN1111 1010b
Given1111 0X0Xb
Slave B:SADDR1111 0011b SADEN1111 1001b
Given1111 0XX1b
Slave C:SADDR1111 0011b
SADENIIII IIUID
Given1111 00X1b

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b).

For slave A, bit 1 is a 0; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves A and B, but not slave C, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

SADDR 0101 0110b SADEN 1111 1100b SADDR OR SADEN1111 111Xb

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b

<u>SADEN1111 1010b</u>

Given1111 1X11b,

Slave B:SADDR1111 0011b

<u>SADEN1111 1001b</u>

Given1111 1X11B,

Slave C:SADDR=1111 0010b

<u>SADEN1111 1101b</u>

Given1111 1111b
```



Programmable Clock-Output

In clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 37). The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency depending on the system oscillator frequency and the value in the RCAP2H and RCAP2L registers:

 $Clock - OutFrequency = \frac{FT2clock}{4 \times (65536 - RCAP2H/RCAP2L)}$

For a 16 MHz system clock in x1 mode, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16}$) to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or different depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.









Registers

Table 45. T2CON Register

T2CON (S:C8h) Timer 2 Control Register

7	6	5	4	3	2	1	0				
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2#	CP/RL2#				
Bit Number	Bit Mnemonic	Description	Description								
7	TF2	Timer 2 Ove TF2 is not se Must be clea Set by hardw	Timer 2 Overflow Flag TF2 is not set if RCLK=1 or TCLK = 1. Must be cleared by software. Set by hardware on timer 2 overflow.								
6	EXF2	Timer 2 Externation Set when a created EXEN2=1. Set to cause is enabled. Must be clear	Timer 2 External Flag Set when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. Set to cause the CPU to vector to timer 2 interrupt routine when timer 2 interrupt is enabled. Must be cleared by software.								
5	RCLK	Receive Clo Clear to use Set to use tir	ck bit timer 1 overfl ner 2 overflov	ow as receive v as receive cl	clock for seria ock for serial p	al port in mode port in mode 1	∋ 1 or 3. I or 3.				
4	TCLK	Transmit Cle Clear to use Set to use tir	Transmit Clock bit Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.								
3	EXEN2	Timer 2 External Enable bit Clear to ignore events on T2EX pin for timer 2 operation. Set to cause a capture or reload when a negative transition on T2EX pin is detected, if timer 2 is not used to clock the serial port.									
2	TR2	Timer 2 Run Control bit Clear to turn off timer 2. Set to turn on timer 2.									
1	C/T2#	Timer/Coun Clear for time Set for count	Timer/Counter 2 Select bit Clear for timer operation (input from internal clock system: F _{OSC}). Set for counter operation (input from T2 input pin).								
0	CP/RL2#	Timer 2 Cap If RCLK=1 or timer 2 overf Clear to auto EXEN2=1. Set to captur	ture/Reload r TCLK=1, CF low. -reload on tim e on negative	bit VRL2# is ignor her 2 overflows transitions or	red and timer i s or negative t n T2EX pin if E	is forced to au ransitions on EXEN2=1.	ito-reload on T2EX pin if				

Reset Value = 0000 0000b Bit addressable

High Speed Output Mode In this mode the CEX output (on port 1) associated with the PCA module will toggle each time a match occurs between the PCA counter and the module's capture registers. To activate this mode the TOG, MAT, and ECOM bits in the module's CCAPMn SFR must be set.





Pulse Width Modulator Mode

All the PCA modules can be used as PWM outputs. The output frequency depends on the source for the PCA timer. All the modules will have the same output frequency because they all share the PCA timer. The duty cycle of each module is independently variable using the module's capture register CCAPLn. When the value of the PCA CL SFR is less than the value in the module's CCAPLn SFR the output will be low, when it is equal to or greater than it, the output will be high. When CL overflows from FF to 00, CCAPLn is reloaded with the value in CCAPHn. the allows the PWM to be updated without glitches. The PWM and ECOM bits in the module's CCAPMn register must be set to enable the PWM mode.



Registers

Table 70. IEN0 Register

IEN0 (S:A8h) Interrupt Enable Register

7	6	5	4	3	2	1	0			
EA	EC	ET2	ES	ET1	EX1	ET0	EX0			
Bit Number	Bit Mnemonic	Description								
7	EA	Enable All II Clear to disa Set to enable If EA=1, each clearing its in	Enable All Interrupt bit Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its interrupt enable bit.							
6	EC	PCA Interru Clear to disa Set to enable	pt Enable ble the PCA in the PCA inte	nterrupt. errupt.						
5	ET2	Timer 2 Ove Clear to disa Set to enable	e rflow Interru ble Timer 2 ov e Timer 2 over	pt Enable bit verflow interru rflow interrupt.	pt.					
4	ES	Serial Port I Clear to disa Set to enable	Serial Port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.							
3	ET1	Timer 1 Ove Clear to disa Set to enable	Timer 1 Overflow Interrupt Enable bit Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.							
2	EX1	External Inte Clear to disa Set to enable	External Interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.							
1	ET0	Timer 0 Ove Clear to disa Set to enable	Timer 0 Overflow Interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.							
0	EX0	External Internation Clear to disa Set to enable	errupt 0 Enal ble external ir e external inte	ble bit nterrupt 0. rrupt 0.						

Reset Value = 0000 0000b bit addressable





Table 71. IEN1 Register

IEN1 (S:E8h) Interrupt Enable Register

7	6	5	4	3	2	1	0		
-	-	-	-	-	-	EADC	-		
Bit Number	Bit Mnemonic	Description							
7	-	Reserved The value re	ad from this b	it is indetermi	nate. Do not s	et this bit.			
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
5	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
4	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.						
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.							
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.							
1	EADC	ADC Interrupt Enable bit Clear to disable the ADC interrupt. Set to enable the ADC interrupt.							
0	-	Reserved The value re	ad from this b	it is indetermi	nate. Do not s	et this bit.			

Reset Value = xxxx xx00b bit addressable

Electrical Characteristics

Absolute Maximum Ratings*

Ambiant Temperature Under Bias:	*NOTICE:
I = industrial40°C to 85°C	
Storage Temperature65°C to + 150°C	
Voltage on V_{CC} from V_{SS} 0.5V to + 6V	
Voltage on Any Pin from V_{SS} -0.5V to V_{CC} + 0.2V	
Power Dissipation 1W	

DC Parameters for Standard Voltage

TA = -40°C to +85°C; V_{SS} = 0V; V_{CC} = 3V to 5.5V; F = 0 to 40 MHz

Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability. The power dissipation is based on the maximum allowable die temperature and the thermal resistance of the package.

Table 76.	6. DC Parameters in Standard Voltage								
Symbol	Parameter	Min	Typ ⁽⁵⁾	Мах	Unit	Test Conditions			
V _{IL}	Input Low Voltage	-0.5		0.2Vcc - 0.1	V				
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V				
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V				
V _{OL}	Output Low Voltage, ports 1, 2, 3 and $4^{(6)}$			0.3 0.45 1.0	> > >	$\begin{split} I_{OL} &= 100 \; \mu A^{(4)} \\ I_{OL} &= 1.6 \; m A^{(4)} \\ I_{OL} &= 3.5 \; m A^{(4)} \end{split}$			
V _{OL1}	Output Low Voltage, port 0, ALE, PSEN ⁽⁶⁾			0.3 0.45 1.0	V V V	$\begin{split} I_{OL} &= 200 \; \mu A^{(4)} \\ I_{OL} &= 3.2 \; m A^{(4)} \\ I_{OL} &= 7.0 \; m A^{(4)} \end{split}$			
V _{OH}	Output High Voltage, ports 1, 2, 3, 4 and 5	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			> > >	I _{OH} = -10 μA I _{OH} = -30 μA I _{OH} = -60 μA			
V _{OH1}	Output High Voltage, port 0, ALE, PSEN	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	I _{OH} = -200 μA I _{OH} = -3.2 mA I _{OH} = -7.0 mA			
R _{RST}	RST Pulldown Resistor	20	40	200	kΩ				
I _{IL}	Logical 0 Input Current ports 1, 2, 3 and 4			-50	μA	Vin = 0.45V			
ILI	Input Leakage Current			±10	μA	0.45V < Vin < V _{CC}			
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3 and 4			-650	μA	Vin = 2.0V			
C _{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C			
I _{PD}	Power-down Current		160	350	μA	$3V < V_{CC} < 5.5V^{(3)}$			
I _{cc}	Power Supply Current	I _{CCOP} = ICC_FLASH_W I _{CCIDLE}	= 0.7 Freq (MHz) 'RITE ⁽⁷⁾ =0.4 Fred = 0.6 Freq (MHz)		$3V < V_{CC} < 5.5V^{(1)(2)}$				





DC Parameters for A/D Converter

Symbol	Parameter	Min	Typ ⁽¹⁾	Мах	Unit	Test Conditions
AVin	Analog input voltage	Vss- 0.2		Vref + 0.2	V	
Rref ⁽²⁾	Resistance between Vref and Vss	12	16	24	kΩ	
Vref	Reference voltage	2.40		3.00	V	
Cai	Analog input Capacitance		60		pF	During sampling
Rai	Analog input Resistor			400	Ω	During sampling
INL	Integral non linearity		1	2	lsb	
DNL	Differential non linearity		0.5	1	lsb	
OE	Offset error	-2		2	lsb	

Notes: 1. Typicals are based on a limited number of samples and are not guaranteed.

2. With ADC enabled.

AC Parameters

Symbols

Explanation of the AC Each timing symbol has 5 characters. The first character is always a "T" (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{AVLL} = Time for Add<u>ress Valid</u> to ALE Low.

 T_{LLPL} = Time for ALE Low to PSEN Low.

TA = -40°C to +85°C; $V_{SS} = 0V$; $V_{CC} = 5V \pm 10\%$; F = 0 to 40 MHz.

 $T_A = -40^{\circ}C$ to $+85^{\circ}C$; $V_{SS} = 0V$; $V_{CC} = 5V \pm 10\%$.

(Load Capacitance for port 0, ALE and PSEN = 60 pF; Load Capacitance for all other outputs = 60 pF.)

Table 78, Table 81 and Table 84 give the description of each AC symbols.

Table 79, Table 83 and Table 85 give for each range the AC parameter.

Table 80, Table 83 and Table 86 give the frequency derating formula of the AC parameter for each speed range description. To calculate each AC symbols: Take the x value and use this value in the formula.

Example: T_{LLIV} and 20 MHz, Standard clock.

x = 30 nsT = 50 ns $T_{CCIV} = 4T - x = 170 \text{ ns}$

External Program Memory Characteristics

Table 78. Symbol Description

Symbol	Parameter
Т	Oscillator clock period
T _{LHLL}	ALE pulse width
T _{AVLL}	Address Valid to ALE
T _{LLAX}	Address Hold After ALE
T _{LLIV}	ALE to Valid Instruction In
T _{LLPL}	ALE to PSEN
T _{PLPH}	PSEN Pulse Width
T _{PLIV}	PSEN to Valid Instruction In
T _{PXIX}	Input Instruction Hold After PSEN
T _{PXIZ}	Input Instruction Float After PSEN
T _{AVIV}	Address to Valid Instruction In
T _{PLAZ}	PSEN Low to Address Float

Table 79. AC Parameters for a Fix Clock (F = 40 MHz)

Symbol	Min	Мах	Units
Т	25		ns
T _{LHLL}	40		ns
T _{AVLL}	10		ns
T _{LLAX}	10		ns
T _{LLIV}		70	ns
T _{LLPL}	15		ns
T _{PLPH}	55		ns
T _{PLIV}		35	ns
T _{PXIX}	0		ns
T _{PXIZ}		18	ns
T _{AVIV}		85	ns
T _{PLAZ}		10	ns



External Data Memory Characteristics

Table 81. Symbol Description

Symbol	Parameter
T _{RLRH}	RD Pulse Width
T _{WLWH}	WR Pulse Width
T _{RLDV}	RD to Valid Data In
T _{RHDX}	Data Hold After RD
T _{RHDZ}	Data Float After RD
T _{LLDV}	ALE to Valid Data In
T _{AVDV}	Address to Valid Data In
T _{LLWL}	ALE to WR or RD
T _{AVWL}	Address to WR or RD
T _{QVWX}	Data Valid to WR Transition
Τ _{QVWH}	Data set-up to WR High
T _{WHQX}	Data Hold After WR
T _{RLAZ}	RD Low to Address Float
T _{WHLH}	RD or WR High to ALE high

Table 82. AC Parameters for a Variable Clock (F = 40 MHz)

Symbol	Min	Max	Units
T _{RLRH}	130		ns
T _{WLWH}	130		ns
T _{RLDV}		100	ns
T _{RHDX}	0		ns
T _{RHDZ}		30	ns
T _{LLDV}		160	ns
T _{AVDV}		165	ns
T _{LLWL}	50	100	ns
T _{AVWL}	75		ns
T _{QVWX}	10		ns
T _{QVWH}	160		ns
T _{WHQX}	15		ns
T _{RLAZ}		0	ns
T _{WHLH}	10	40	ns



A/T89C51AC2

External Clock Drive Waveforms

AC Testing Input/Output

Waveforms



INPUT/OUTPUT



AC inputs during testing are driven at V_{CC} - 0.5 for a logic "1" and 0.45V for a logic "0". Timing measurement are made at V_{IH} min for a logic "1" and V_{IL} max for a logic "0".

Float Waveforms



For timing purposes as port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \ge \pm 20$ mA.







This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ($T_A=25^{\circ}C$ fully loaded) RD and WR propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.



Ordering Information

Table 91. Possible Order Entries

Part Number	Supply Voltage	Temperature Range	Max Frequency	Package	Packing	
T89C51AC2-RLTIM						
T89C51AC2-SLSIM	OBSOLETE					
AT89C51AC2-RLTUM	2)/ to 5 5)/ . 109/	Industrial & Green	40 MHz	VQFP44	Tray	
AT89C51AC2-SLSUM	3V 10 5.5V <u>+</u> 10%			PLCC44	Stick	

Datasheet Change Log for A/T89C51AC2

Changes from 4127D -02/03 to 4127E - 01/05

- 1. Changed value of IPDMAX to 400, Section "Electrical Characteristics", page 101.
- 2. PCA , CPS0, register correction, Section "PCA Registers", page 81.
- 3. Cross Memory section added. Section "Operation Cross Memory Access", page 44.

Changes from 4127E - 01/05 to 4127F - 03/05

- 1. Changed product part number from "T89C51AC2" to "A/T89C51AC2".
- 2. Added "Green" product ordering information.
- 3. Clarification to Mode Switching Waveform diagrams. See page page 16.

Changes from 4127F - 03/05 to 4127G - 05/06

1. Minor corrections throughout the document.

Changes from 4127G - 05/06 to 4127H - 02/08

1. Removal of non-green part numbers from ordering information.

